

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number: 10/680783							
Confirmation Number: 5859							
First Named Applicant: William Jones							
Attorney Docket Number:							
Search string: (5882165 or 5888050 or 5898727 or 5900107 or 5904737 or 5928389 or 5932100 or 5934856 or 5934991 or 5979306 or 5980648 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6035871 or 6037277 or 6053348 or 6056008 or 6067728 or 6077053 or 6077321 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6186722 or 6203582 or 6216364 or 6228563 or 6235634 or 6239038 or 6241825 or 6251250 or 6244121 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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<input checked="" type="checkbox"/>	1	5882165	1999-03-16	Maydan et al.			
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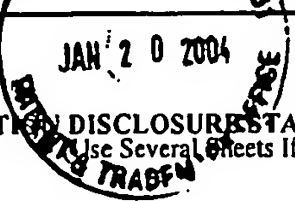
Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 3 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
1/24	9/23/05

FORM PTO-1449 (Modified)				U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)						Applicant: William Dale Jones			
(37 CFR § 1.98(b))						Filing Date: October 6, 2003		Group Art Unit: 1765	
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Examiner: <i>[Signature]</i>					Date Considered: 9/23/05				
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicant: William Dale Jones			
(37 CFR § 1.98(h))				Filing Date: October 6, 2003		Group Art Unit: 1765	

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		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
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Examiner: 11K	Date Considered: 9/23/05
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EXAMINER:	Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.
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1/12/04

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8
Stylesheet Version v1.8.0

Title of
Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR
WAFER

Application Number: 10/680783 *10/680783*
Confirmation Number: 5859
First Named Applicant: William Jones
Attorney Docket Number:
Search string: (6521466 or 6541278 or 6546946 or 6550484 or 6558475 or
6561213 or 6561220 or 6561481 or 6561767 or 6564826 or
5217043 or 20020001929).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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2	2	6541278	2003-04-01	Morita et al.	B1		
3	3	6546946	2003-04-15	Dunmire	B1		
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

Init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1	1	20020001929	2002-01-03	Biberger et al.	A1		

Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 4 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
1/12/04	9/23/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

JAN 20 2004

Title of Invention HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Application Number: 10/680783 *10/680783*

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (2617719 or 2625886 or 3744660 or 3968885 or 4029517 or 4091643 or 4245154 or 4341592 or 4355937 or 4367140 or 4406596 or 4422651 or 4474199 or 4522788 or 4549467 or 4592306 or 4601181 or 4626509 or 4670126 or 4682937 or 4693777 or 4749440 or 4778356 or 4788043 or 4789077 or 4823976 or 4825808 or 4827867 or 4838476 or 4865061 or 4879431 or 4917556 or 4924892 or 4951601 or 4960140 or 4983223 or 5011542 or 5044871 or 5062770 or 5071485 or 5105556 or 5143103 or 5167716 or 5169296 or 5169408 or 5185296 or 5186718 or 5188515 or 5190373 or 5191993).pn.

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Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 1 out of a total of 4 electronic filings.

Signature

Examiner Name	Date
Wm KU	9/23/05

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Confirmation Number:	5859						
First Named Applicant:	William Jones						
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Search string:	(S193560 or S195878 or S213485 or S221019 or S222876 or S224504 or S236669 or S237824 or S240390 or S243821 or S246500 or S251776 or S267455 or S280693 or S285352 or S288333 or S313965 or S314574 or S328722 or S337446 or S339844 or S355901 or S368171 or S370741 or S377705 or S401322 or S404894 or S412958 or S417768 or S433334 or S447294 or S503176 or S505219 or S509431 or S526834 or S533538 or S571330 or S589224 or S621982 or S629918 or S644855 or S649809 or S656097 or S669251 or S702228 or S706319 or S746008 or S797719 or S798126 or S881577).pn.						
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Remarks

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Examiner Name	Date

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First Named Applicant:	William Jones						
Attorney Docket Number:							
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	3	5898727	1999-04-27	Fujikawa et al.			
	4	5900107	1999-05-04	Murphy et al.			
	5	5904737	1999-05-18	Preston et al.			
	6	5928389	1999-07-27	Jevtic			
	7	5932100	1999-08-03	Yager et al.			

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8	5934856	1999-08-10	Asahawa et al.
9	5934991	1999-08-10	Rush
10	5979306	1999-11-09	Fujikawa et al.
11	5980648	1999-11-09	Adler
12	5981399	1999-11-09	Kawamura et al.
13	5989342	1999-11-23	Ikedo et al.
14	6005226	1999-12-21	Aschmeier et al.
15	6017820	2000-01-25	Ting et al.
16	6029371	2000-02-29	Kamihara et al.
17	6035871	2000-03-14	Eul-Yeol
18	6037277	2000-03-14	Masakara et al.
19	6053348	2000-04-25	Morch
20	6056008	2000-05-02	Adams et al.
21	6067728	2000-05-30	Farmer et al.
22	6077053	2000-06-20	Fujikawa et al.
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26	6097015	2000-08-01	McCullough et al.
27	6128830	2000-10-10	Bettcher et al.
28	6145519	2000-11-14	Konishi et al.
29	6159295	2000-12-12	Masakara et al.
30	6164297	2000-12-26	Kamihara
31	6186722	2001-02-13	Shiral
32	6203582	2001-03-20	Berner et al.
33	6216364	2001-04-17	Tanaka et al.
34	6228563	2001-05-08	Starov et al.
35	6235634	2001-05-22	White et al.
36	6239038	2001-05-29	Wen
37	6241825	2001-06-05	Wyman
38	6241250	2001-06-26	Kelgier
39	6244121	2001-06-12	Hunter

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43	6334266	2002-01-01	Moritz et al.	81
44	6344174	2002-02-05	Miller et al.	81
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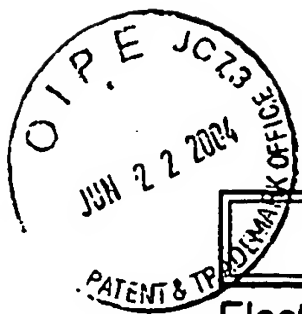
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Non US Patent and Publication references shall be filed under a separate paper transmittal.
The current electronic filing contains part 3 out of a total of 4 electronic filings.

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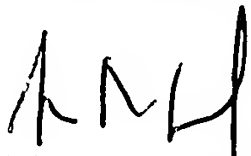
Examiner Name	Date

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number: 10/680783 .							
Confirmation Number: 5859							
First Named Applicant: William Jones							
Attorney Docket Number:							
Search string: (5186594 or 5769588 or 5906866 or 5975492 or 6122566 or 6355072 or 6454519 or 20030205510 or 20040020518).pn.							
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Examiner Name				Date			

FORM PTO-1449 (Modified) JUN 25 2004 INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR § 1.98(b))		U.S. Department of Commerce Patent and Trademark Office		Attorney Docket No.: SSI-04001		Serial No.: 10/680,783	
Applicants: William D. Jones				Filing Date: October 6, 2003		Group Art Unit: 1765	

U.S. PATENT DOCUMENTS							
Examiner Initials	Serial / Patent Number	Issue Date	Applicant / Patentee	Class	Subclass	Filing Date	
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	AO						
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1W	AQ	JP 8-206485	08/13/96	JP	B01J	3/06		X
	AR							
	AS							

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)		
	AT	
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	AV	
	AW	
	AX	
	AY	
	AZ	

Examiner: <u>1W</u>	Date Considered: <u>9/23/05</u>
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

Stylesheet Version v1.8.0

Title of
Invention

HIGH-PRESSURE CHAMBER FOR A SEMICONDUCTOR WAFER

Application Number: 10/680783

10/680783

Confirmation Number: 5859

First Named Applicant: William Jones

Attorney Docket Number:

Search string: (5186594 or 5769588 or 5906866 or 5975492 or 6122566 or 6355072 or 6454519 or 2003020510 or 20040020518).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents.

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	4	5975492	1999-11-02	Brenes			
	5	6122566	2000-09-19	Nguyen et al.			
	6	6355072	2002-03-12	Racette et al.	B1		
	7	6454519	2002-09-24	Toshima et al.	B1		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

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Date


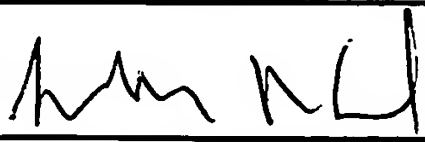
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
<p>Application Number : 10/680783 </p> <p>Confirmation Number: 5859</p> <p>First Named Applicant: William Jones</p> <p>Attorney Docket Number:</p> <p>Art Unit:</p> <p>Examiner:</p> <p>Search string: (3623627 or 4426358 or 4574184 or 5374829 or 5474410 or 5879459 or 6048494 or 6062853 or 6089377 or 6406782 or 20010050096).pn</p>							
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FORM PTO-1449
(Modified)

JAN 10 2005

U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: SSI-04001

Serial No.: 10/680,783

INFORMATIONAL DISCLOSURE STATEMENT BY APPLICANT
(Use Several Sheets If Necessary)

Applicants: William Dale Jones

Filing Date: October 6, 2003

Group Art Unit: 1765

(37 CFR § 1.98(b))

U.S. PATENT DOCUMENTS

Examiner Initials		Serial / Patent Number	Issue Date	Applicant / Patentee	Class	Subclass	Filing Date
	AA						
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FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS

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							Yes	No
1/2	AK	JP 40 5283511 A	10/29/93	JP	H01L	21/68	X	
1/2	AL	JP 2001-77074	03/23/01	JP	H01L	21/304	X	
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	AN							
	AO							

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

	AP	
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Examiner:

Date Considered:

EXAMINER:

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number:	10/680783	*10/680783*					
Confirmation Number:	5859						
First Named Applicant:	William Jones						
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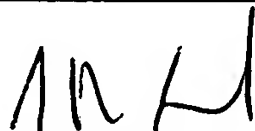
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1/18/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0


Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER																																																																														
<div>Application Number : 10/680783 </div> <div>Confirmation Number: 5859</div> <div>First Named Applicant: William Jones</div> <div>Attorney Docket Number:</div> <div>Art Unit:</div> <div>Examiner:</div> <div>Search string: (3681171 or 4827867 or 5009738 or 6221781 or 6306564 or 6497239 or 20030005948).pn</div> <p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><input checked="" type="checkbox"/></td><td>1</td><td>3681171</td><td>1972-08-01</td><td>Toku Hojo et al.</td><td></td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>2</td><td>4827867</td><td>1989-05-09</td><td>Takei et al.</td><td></td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>3</td><td>5009738</td><td>1991-04-23</td><td>Gruenwald et al.</td><td></td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>4</td><td>6221781</td><td>2001-04-24</td><td>Siefering et al.</td><td>B1</td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>5</td><td>6306564</td><td>2001-10-23</td><td>Mullee</td><td>B1</td><td></td><td></td></tr><tr><td><input checked="" type="checkbox"/></td><td>6</td><td>6497239</td><td>2002-12-24</td><td>Farmer et al.</td><td>B2</td><td></td><td></td></tr></tbody></table> <p>US Published Applications</p> <p>Note: Applicant is not required to submit a paper copy of cited US Published Applications</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><input checked="" type="checkbox"/></td><td>1</td><td>20030005948</td><td>2003-01-09</td><td>Matsuno et al.</td><td>A1</td><td></td><td></td></tr></tbody></table> <div>Signature  9/23/05</div>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	<input checked="" type="checkbox"/>	1	3681171	1972-08-01	Toku Hojo et al.				<input checked="" type="checkbox"/>	2	4827867	1989-05-09	Takei et al.				<input checked="" type="checkbox"/>	3	5009738	1991-04-23	Gruenwald et al.				<input checked="" type="checkbox"/>	4	6221781	2001-04-24	Siefering et al.	B1			<input checked="" type="checkbox"/>	5	6306564	2001-10-23	Mullee	B1			<input checked="" type="checkbox"/>	6	6497239	2002-12-24	Farmer et al.	B2			init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass	<input checked="" type="checkbox"/>	1	20030005948	2003-01-09	Matsuno et al.	A1		
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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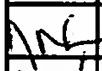
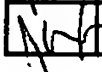
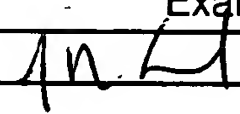
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	4	6109296	2000-08-29	Austin																																																																																							
	5	6465403	2002-10-15	Skee	B1																																																																																						
	6	6508259	2003-01-21	Tseronis et al.	B1																																																																																						
	7	6509141	2003-01-21	Mullee	B2																																																																																						
	8	6635565	2003-10-21	Wu et al.	B2																																																																																						
AK	9	6641678	2003-11-04	DeYoung et al.	B2																																																																																						
Examiner Name	Date																																																																																										
AK	9/23/05																																																																																										

4/8/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number :	10/680783						
Confirmation Number:	5859						
First Named Applicant:	William Jones						
Attorney Docket Number:							
Art Unit:							
Examiner:							
Search string:	(4391511 or 6722642).pn						
<p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p>							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4391511	1983-07-05	Akiyama et al.			
	2	6722642	2004-04-20	Sutton et al.	B1		
Signature							
Examiner Name				Date			
				9/23/05			

5/16/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
<div>Application Number : 10/680783 </div> <div>Confirmation Number: 5859</div> <div>First Named Applicant: William Jones</div> <div>Attorney Docket Number:</div> <div>Art Unit:</div> <div>Examiner:</div> <div>Search string: (20030036023 or 20040134515).pn</div>							
<p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p>							
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1/2	1	20030036023	2003-02-20	Moreau et al.	A1		
1/2	2	20040134515	2004-07-15	Castrucci	A1		
Signature							
Examiner Name				Date			
A. L.				9/23/05			

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER
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Application Number : 10/680783
Confirmation Number: 5859
First Named Applicant: William Jones
Attorney Docket Number:
Art Unit:
Examiner:
Search string: (5494526 or 6333268).pn



Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
10/680783	1	5494526	1996-02-27	Paranjpe			
10/680783	2	6333268	2001-12-25	Starov et al.	B1		

Signature

Examiner Name	Date
10/680783	9/23/05

7/19/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
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Application Number : 10/680783

Confirmation Number: 5859


First Named Applicant: William Jones

Attorney Docket Number:

Art Unit:

Examiner:

Search string: (5306350 or 5772783 or 5850747 or 5858107 or 5943721 or 5946945 or 5970554 or 6070440 or 6264753 or 6612317 or 6736149 or 6764552 or 6805801 or 6851148 or 6874513).pn



Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
✓	1	5306350	1994-04-26	Hoy et al.			
	2	5772783	1998-06-30	Stucker			
	3	5850747	1998-12-22	Roberts et al.			
	4	5858107	1999-01-12	Chao et al.			
	5	5943721	1999-08-31	Lerette et al.			
	6	5946945	1999-09-07	Kegler et al.			
	7	5970554	1999-10-26	Shore et al.			
	8	6070440	2000-06-06	Malchow et al.			
	9	6264753	2001-07-24	Chao et al.			
	10	6612317	2003-09-02	Costantini et al.			
	11	6736149	2004-05-18	Biberger et al.	B2		
	12	6764552	2004-07-20	Joyce et al.	B1		
	13	6805801	2004-10-19	Humayun et al.	B1		
✓	14	6851148	2005-02-08	Preston et al.	B2		

9/2	15	6874513	2005-04-05	Yamagata et al.	B2		
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Signature

Examiner Name	Date

7h L1


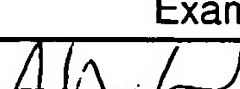
9/23/05

8/17/05

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number :		10/680783					
Confirmation Number:		5859					
First Named Applicant:		William Jones					
Attorney Docket Number:							
Art Unit:							
Examiner:							
Search string:		(20030051741).pn					
<p>Certification: This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p> <p>That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.</p>							
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
1	1	20030051741	2003-03-20	DeSimone et al.			
Signature							
Examiner Name				Date			
				9/23/05			